

ABSTRACT

CUTTING APPARATUS AND WAFER CUTTING METHOD

Disclosed herein is a cutting apparatus including a chuck table for holding a workpiece, a cutting unit for cutting the workpiece held on the chuck table, and a feeding mechanism for relatively moving the chuck table and the cutting unit. The cutting unit includes a spindle adapted to be rotationally driven, a rotatable cutting blade mounted on the spindle and having a peripheral cutting edge, a cutting water nozzle for supplying a cutting water to the cutting blade, a photocatalyst member provided so as to come into contact with the cutting water supplied from the cutting water nozzle, and a light applying unit for exciting the photocatalyst member to thereby give an oxidizing power due to hydroxy radicals to the cutting water.

(Figure 6)